

IN THE CLAIMS:

Claim 3 has been amended herein. All of the pending claims 1 through 18 are presented below. This listing of claims will replace all prior versions and listings of claims in the application. Please enter these claims as amended.

Listing of Claims:

1. (Previously presented) A method for fabricating at least one emission structure, comprising:  
forming at least one conductive structure extending across at least a portion of a substrate;  
substantially removing a longitudinal portion of the at least one conductive structure to define at least one conductive layer having a width that is oriented substantially perpendicular to the substrate, the substrate being exposed along a length of the at least one conductive layer; and  
forming at least one emission structure adjacent the at least one conductive layer.
2. (Previously presented) The method of claim 1, wherein forming the at least one emission structure includes forming an emitter tip.
3. (Currently amended) The method of claim 2, wherein forming the at least one emission structure further includes forming a resistor corresponding to the ~~at least one emitter~~ tip.
4. (Previously presented) The method of claim 3, wherein forming the resistor comprises forming the resistor adjacent to the at least one conductive layer.
5. (Previously presented) The method of claim 1, wherein forming the at least one emission structure comprises forming a plurality of lines of emission structures.

6. (Previously presented) The method of claim 5, wherein substantially removing comprises electrically isolating at least one emission structure located along a first line of the plurality of lines from at least one emission structure located along an adjacent, second line of the plurality of lines.

7. (Previously presented) The method of claim 1, wherein forming the at least one conductive structure comprises:  
disposing a layer comprising conductive material over the substrate; and  
patterning the layer.

8. (Previously presented) The method of claim 1, wherein forming the at least one emission structure comprises forming the at least one emission structure from at least one of semiconductive material and conductive material.

9. (Previously presented) The method of claim 1, wherein forming the at least one emission structure comprises forming the at least one emission structure so as to extend over a lateral edge of the at least one conductive structure.

10. (Previously presented) A method for fabricating at least one emission structure, comprising:  
forming at least one conductive structure that extends at least partially across a substrate;  
forming at least one emitter tip and a corresponding resistor adjacent to the at least one conductive structure; and  
substantially removing at least a longitudinal portion of the at least one conductive structure along substantially an entire length thereof to define at least one conductive layer having a width that is oriented substantially perpendicular to the substrate.

11. (Previously presented) The method of claim 10, wherein forming the at least one conductive structure comprises:

disposing a layer comprising conductive material on the substrate; and  
patterning the layer.

12. (Previously presented) The method of claim 10, wherein forming the at least one emitter tip comprises forming the at least one emitter tip from at least one of semiconductive material and conductive material.

13. (Previously presented) The method of claim 10, wherein forming the corresponding resistor comprises forming the corresponding resistor from at least one of semiconductive material and conductive material.

14. (Previously presented) The method of claim 10, wherein forming the at least one emitter tip comprises:

disposing at least one layer comprising at least one of semiconductive material and conductive material over the substrate and the at least one conductive structure;

removing a longitudinal portion of at least one region of the at least one layer located over the at least one conductive structure to expose at least a substantially longitudinal portion of the at least one conductive structure; and

patterning at least one remaining portion of the at least one layer.

15. (Previously presented) The method of claim 14, wherein patterning the at least one remaining portion of the at least one layer includes defining the at least one emitter tip from the at least one layer.

16. (Previously presented) The method of claim 15, wherein patterning the at least one remaining portion of the at least one layer further includes forming the corresponding resistor.

17. (Previously presented) The method of claim 10, wherein substantially removing comprises leaving at least a lateral edge of the at least one conductive structure along substantially the entire length thereof.

18. (Previously presented) The method of claim 10, wherein forming the at least one emitter tip comprises forming the at least one emitter tip so as to extend over a lateral edge of the at least one conductive structure.